ME7609D/ME7609D-G

P-Channel 30-V (D-S) MOSFET, ESD Producted

GENERAL DESCRIPTION

The ME7609D P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

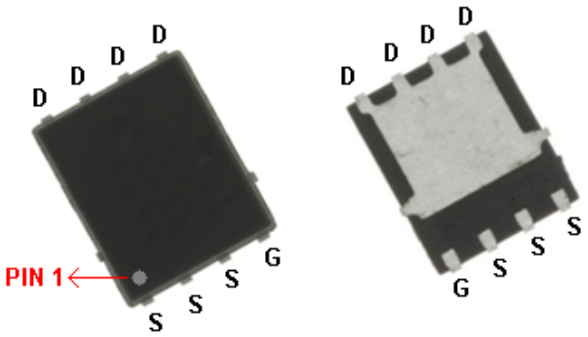
- $R_{DS(ON)}$ ≦19.5mΩ@V_{GS}=-10V
- $R_{DS(ON)}$ ≦40mΩ@V_{GS}=-4.5V

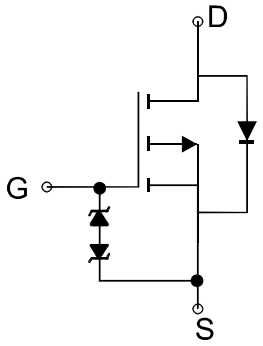
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch
- DSC

PIN CONFIGURATION

PowerDFN 5x6





Ordering Information: ME7609D (Pb-free)

ME7609D-G (Green product-Halogen free)

Absolute Maximum Ratings (T_j=25℃ Unless Otherwise Noted)

Parameter		Symbol	Maximum	Unit
Drain-Source Voltage		V_{DSS}	-30	V
Gate-Source Voltage		V_{GSS}	±25	V
Continuous Drain Current	T_A=25℃	I_D	-9.4	A
	T_A=70℃		-7.6	
Pulsed Drain Current		I_{DM}	-38	A
Maximum Power Dissipation	T_A=25℃	P_D	2.8	W
	T_A=70℃		1.8	
Operating Junction Temperature		T_J	-55 to 150	℃
Thermal Resistance-Junction to Ambient*		$R_{\theta JA}$	45	℃/W
Thermal Resistance-Junction to Case*		$R_{\theta JC}$	3.3	℃/W

*The device mounted on 1in^2 FR4 board with 2 oz copper

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Electrical Characteristics (T_A=25℃ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=-250μA	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=-250μA	-1		-3	V
I_{GSS}	Gate Leakage Current	V_{DS}=0V, V_{GS}=±20V			±15	μA
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-30V, V_{GS}=0V			-1	μA
$R_{DS(ON)}$	Drain-Source On-State Resistance [a]	V_{GS}=-10V, I_D= -8.5A		15.5	19.5	mΩ
		V_{GS}=-4.5V, I_D= -6.3A		30	40	
V_{SD}	Diode Forward Voltage	I_S=-8.5A, V_{GS}=0V		0.8	1.2	V
DYNAMIC						
Qg	Total Gate Charge	V_{DS}=-15V,V_{GS}=-10V, I_D=-8.5A		29		nC
Qg	Total Gate Charge	V_{DS}=-15V,V_{GS}=-4.5V, I_D=-8.5A		15		
Qgs	Gate-Source Charge			6		
Qgd	Gate-Drain Charge			7.5		
Ciss	Input Capacitance	V_{DS}=-15V, V_{GS}=0V,f=1MHz		1130		pF
Coss	Output Capacitance			214		
Crss	Reverse Transfer Capacitance			71		
$t_{d(on)}$	Turn-On Delay Time	V_{DS}=-15V, R_L =15Ω R_{GEN}=6Ω, V_{GS}=-10V		40		ns
tr	Turn-On Rise Time			16		
$t_{d(off)}$	Turn-Off Delay Time			76		
t_f	Turn-Off Fall Time			18		

Note: a.Pulse test: pulse width≦300us, duty cycle≦2%

b. Matsuki reserves the right to improve product design, functions and reliability without notice.

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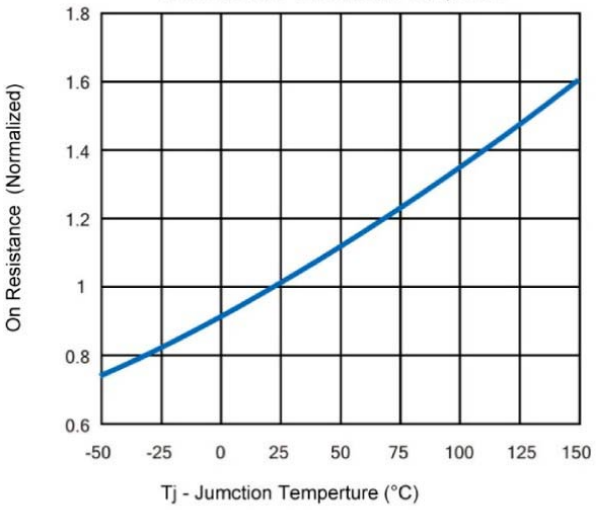
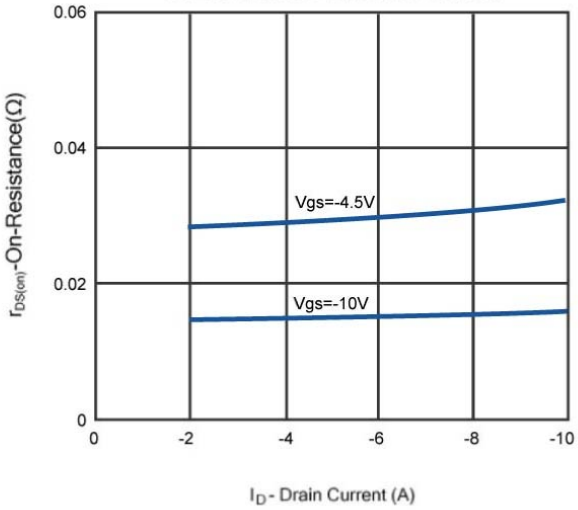
Typical Characteristics (T_J =25℃ Noted)

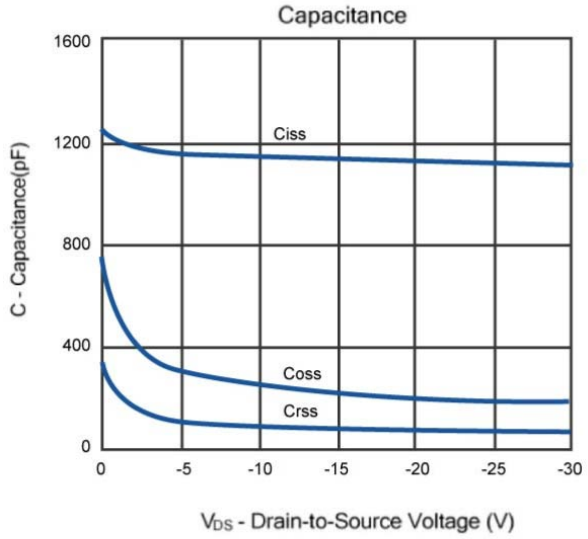
On Resistance vs. Jumction Temperture



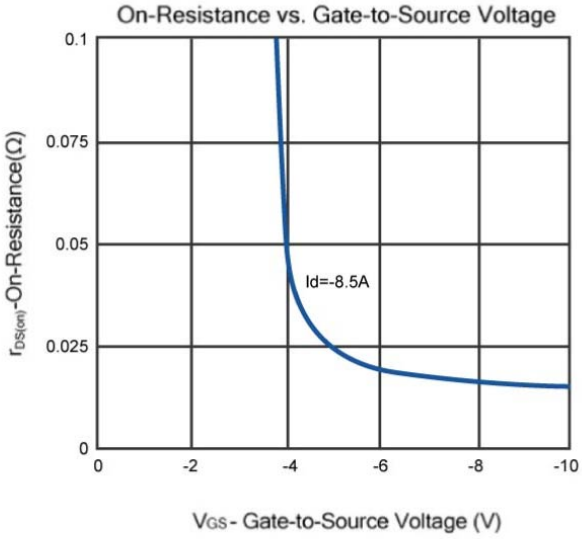
On-Resistance vs. Drain Current



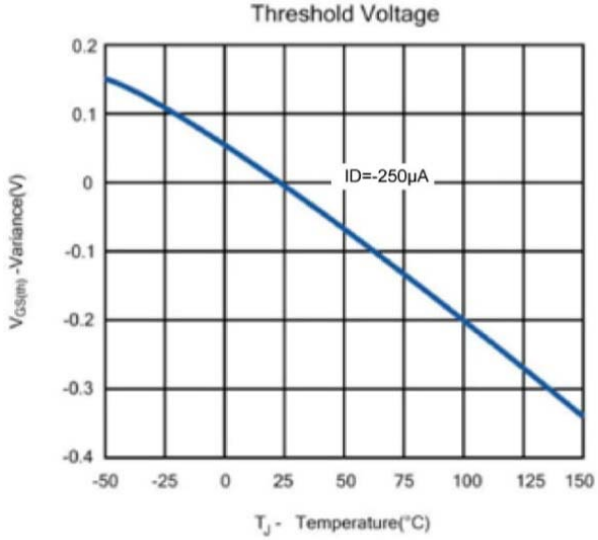
Capacitance



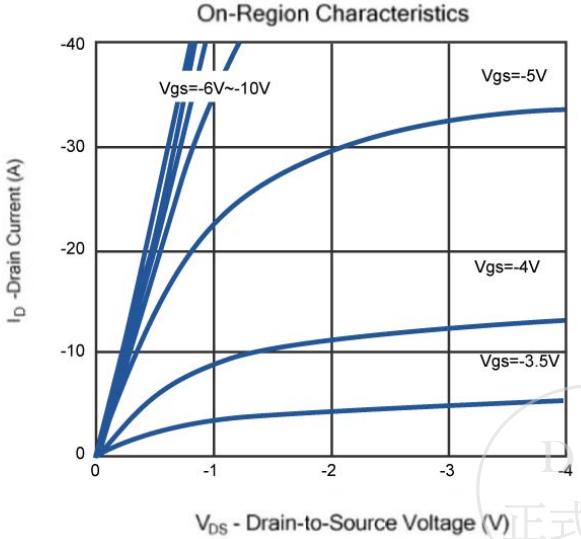
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



On-Region Characteristics



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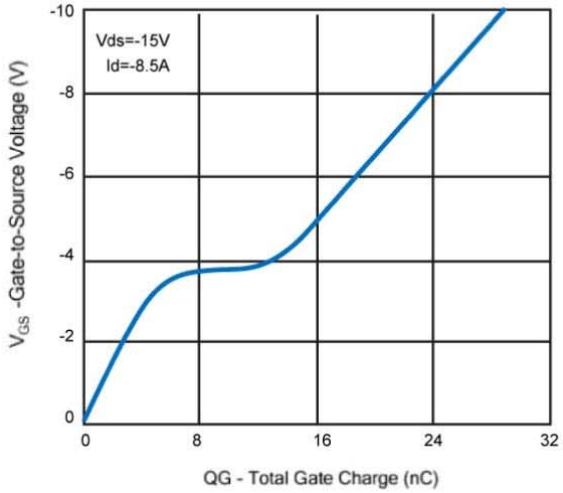
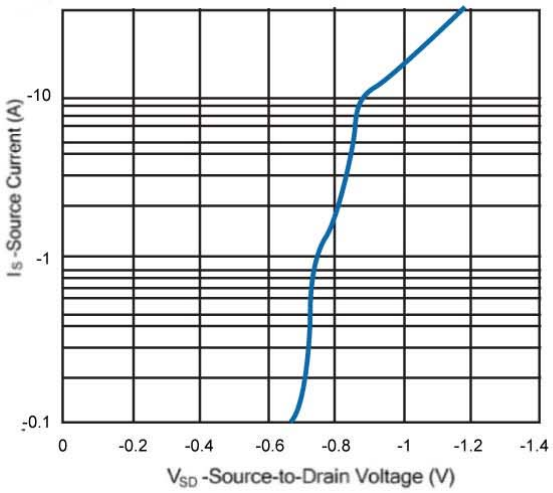
Typical Characteristics (T_J =25℃ Noted)

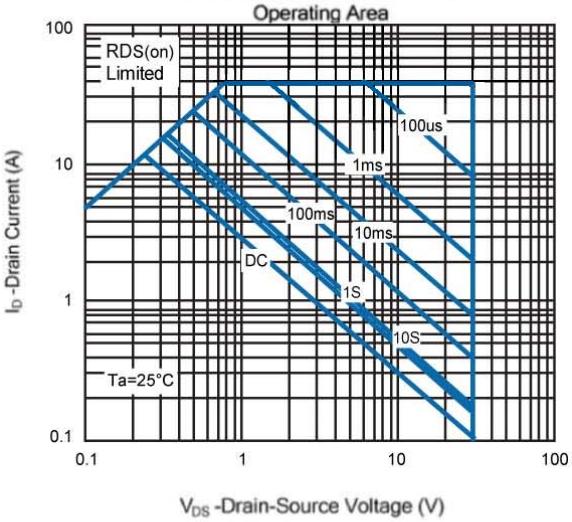
Gate Charge



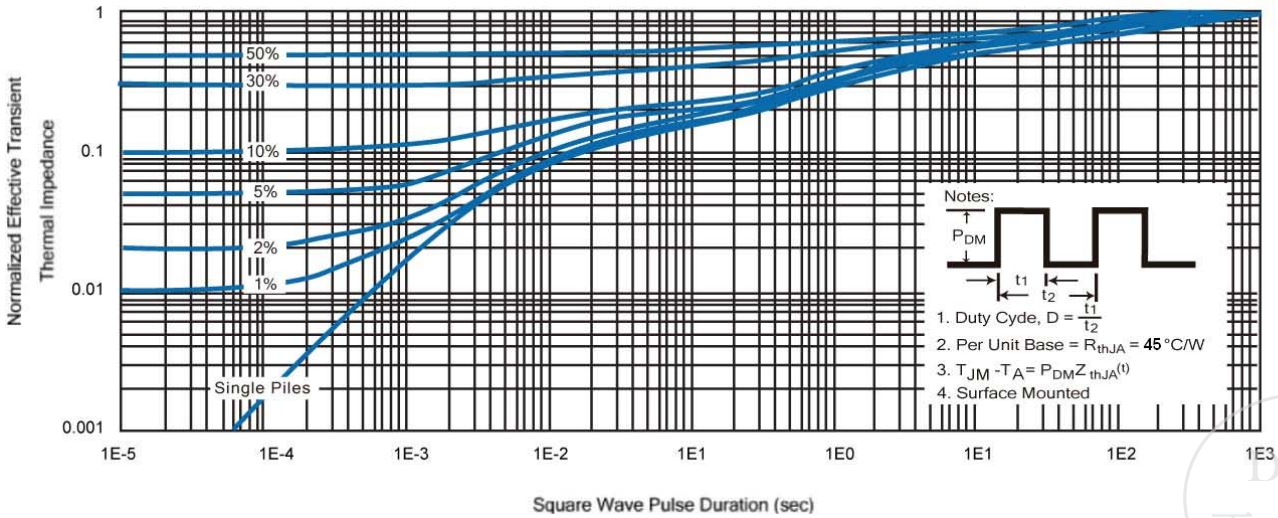
Body-diode characteristics



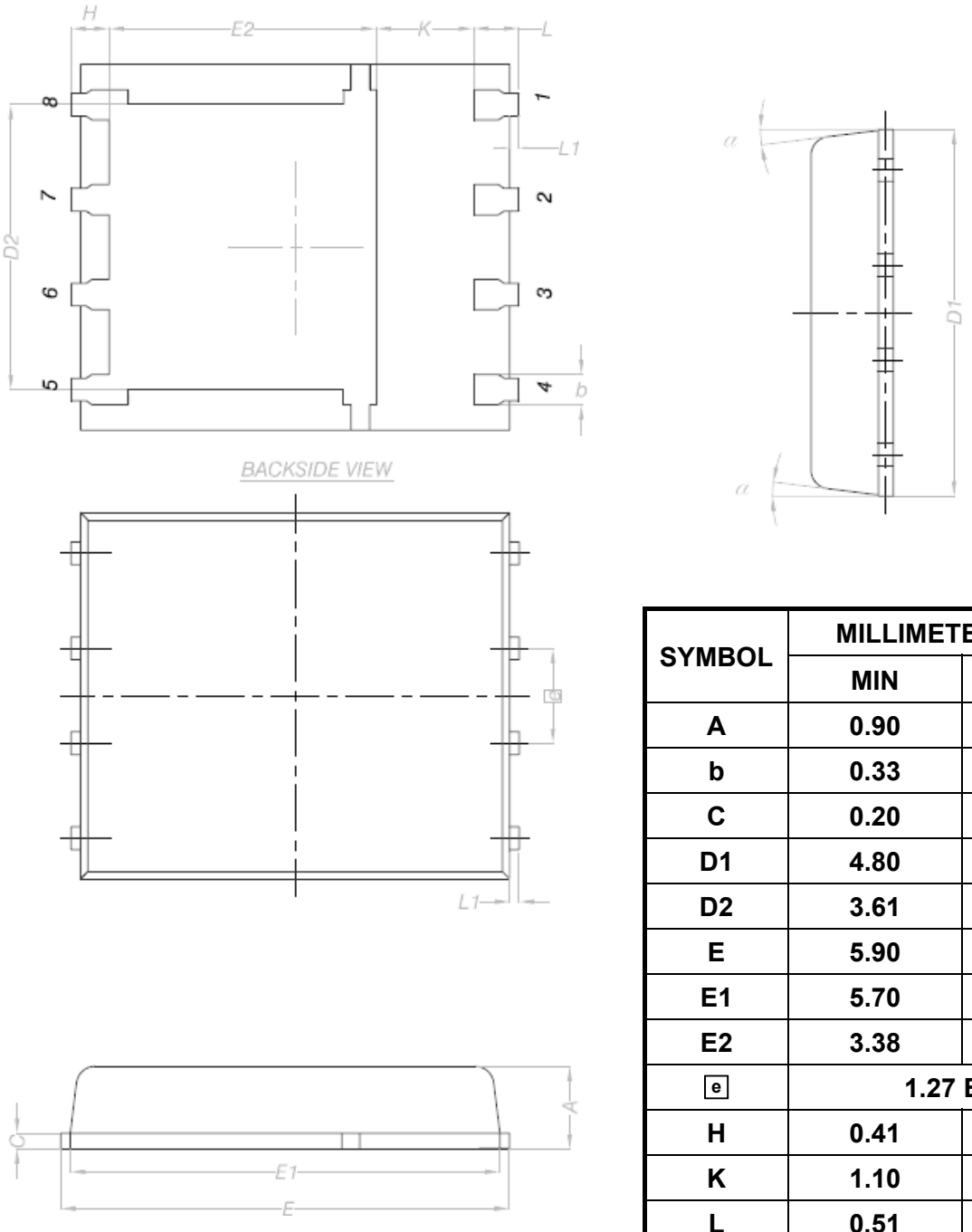
Maximum Forward Biased Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



PowerDFN5x6 Package Outline



SYMBOL	MILLIMETERS (mm)	
	MIN	MAX
A	0.90	1.10
b	0.33	0.51
C	0.20	0.30
D1	4.80	5.00
D2	3.61	3.96
E	5.90	6.10
E1	5.70	5.80
E2	3.38	3.78
e	1.27 BSC	
H	0.41	0.61
K	1.10	-
L	0.51	0.71
L1	0.06	0.20
α	0°	12°